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## IXFN50N120SK



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| MOSFET  |  |   |  |           | Rating            | S              |                            |
|---|--|---|--|-----------|-------------------|----------------|----------------------------|
| Symbol  | Definitions  | Conditions  |  | min.      | typ.              | max.           |                            |
| V <sub>DS(max)</sub>  | max drain source voltage   |   |  |           |                   | 1200           | V                          |
| V <sub>GS(max)</sub><br>V <sub>GS</sub>   | max transient gate source voltage continous gate source voltage  | recommended operational value   |  | -10<br>-5 |                   | +25<br>+20     | V<br>V                     |
| I <sub>D25</sub><br>I <sub>D80</sub><br>I <sub>D100</sub>                                 | drain current  | $\begin{cases} V_{GS} = 20 V \end{cases}$   | $\begin{array}{rl} T_{\rm c} = & 25^{\circ}{\rm C} \\ T_{\rm c} = & 80^{\circ}{\rm C} \\ T_{\rm c} = & 100^{\circ}{\rm C} \end{array}$ |           |                   | 48<br>38<br>33 | A<br>A<br>A                |
| R <sub>DSon</sub>   | static drain source on resistance  | $  \  \   \Big\}   I_{\rm D} = 40   {\rm A};  V_{\rm GS} = 20   {\rm V} \                   $   | $\begin{array}{l} T_{\rm VJ}=~25^{\circ}C\\ T_{\rm VJ}=~150^{\circ}C \end{array}$  |           | 40<br>84          | 52             | mΩ<br>mΩ                   |
| V <sub>GS(th)</sub>   | gate threshold voltage   | $\int I_{D} = 10 \text{ mA; } V_{GS} = V_{DS}$  | $\begin{array}{l} T_{\rm VJ}=~25^{\circ}C\\ T_{\rm VJ}=~150^{\circ}C \end{array}$  | 2.4       | 2.8<br>2.0        | tbd            | V<br>V                     |
| I <sub>DSS</sub>  | drain source leakage current   | $V_{DS} = 1200 \text{ V}; V_{GS} = 0 \text{ V}$   | $T_{VJ} = 25^{\circ}C$   |           | 1                 | 100            | μA                         |
| I <sub>GSS</sub>  | gate source leakage current  | $V_{\rm DS} = 0 \text{ V}; V_{\rm GS} = 20 \text{ V}$   | $T_{VJ} = 25^{\circ}C$   |           |                   | 0.25           | μA                         |
| R <sub>G</sub>  | internal gate resistance   | $f = 1 \text{ MHz}, V_{AC} = 25 \text{ mV}$   |  |           | 1.8               |                | Ω                          |
| C <sub>iss</sub><br>C <sub>oss</sub><br>C <sub>rss</sub>                                  | input capacitance<br>output capacitance<br>reverse transfer (Miller) capacitance   | $ \label{eq:V_DS} \left. \begin{array}{l} \\ \\ \\ \\ \\ \\ \\ \\ \\ \\ \\ \\ \\ \\ \\ \\ \\ \\ \\$   | T <sub>vj</sub> = 25°C   |           | 1895<br>150<br>10 |                | pF<br>pF<br>pF             |
| Q <sub>g</sub><br>Q <sub>gs</sub><br>Q <sub>gd</sub>                                      | total gate charge<br>gate source charge<br>gate drain (Miller) charge  | $ \  \   \Big\} V_{\text{DS}} = 800 \text{ V}; \text{ I}_{\text{D}} = 40 \text{ A}; \text{ V}_{\text{GS}} = -5/20 $   | $V T_{vJ} = 25^{\circ}C$   |           | 115<br>28<br>37   |                | nC<br>nC<br>nC             |
| $\begin{array}{c} t_{d(on)} \\ t_r \\ t_{d(off)} \\ t_f \\ E_{on} \\ E_{off} \end{array}$ | turn-on delay time<br>current rise time<br>turn-off delay time<br>current fall time<br>turn-on energy per pulse<br>turn-off energy per pulse | Inductive switching<br>Free Wheeling Diode: Body Diode<br>$V_{DS} = 800 \text{ V}; I_D = 40 \text{ A}$<br>$V_{GS} = -5/20 \text{ V}; R_G = 2.5 \Omega \text{ (external)}$ | 4  |           |                   |                | ns<br>ns<br>ns<br>mJ<br>mJ |
| $f R_{thJC} \ R_{thJH}$   | thermal resistance junction to case<br>thermal resistance junction to heatsink   | with heatsink compound; IXYS tes  | t setup  |           | 0.72              | 0.6            | K/W<br>K/W                 |

## Source-Drain Diode

| Source-Drain Diode                                    |   |   |  | Ratings |                 |      |               |
|---|---|---|--|---------|-----------------|------|---------------|
| Symbol  | Definitions   | Conditions  |  | min.    | typ.            | max. |               |
| I <sub>S25</sub><br>I <sub>S80</sub>                  | continuous source current   | $V_{GS} = -5 V$   | $\begin{array}{rl} T_{\rm C} = & 25^{\circ}{\rm C} \\ T_{\rm C} = & 80^{\circ}{\rm C} \end{array}$ |         |                 |      | A<br>A        |
| V <sub>SD</sub>                                       | forward voltage drop  | $I_{\rm F} = 20 \text{ A}; V_{\rm GS} = -5 \text{ V}$   | $T_{VJ} = 25^{\circ}C$<br>$T_{VJ} = 150^{\circ}C$  |         | 3.3<br>3.1      |      | V<br>V        |
| t <sub>rr</sub><br>Q <sub>RM</sub><br>I <sub>RM</sub> | reverse recovery time<br>reverse recovery charge (intrinsic diode)<br>max. reverse recovery current | $V_{GS} = -5 \text{ V}; \text{ I}_F = 40 \text{ A}$<br>$V_R = 800 \text{ V}; -di_F/dt = 1000 \text{ A}/\mu\text{s}$ | $T_{vJ} = 25^{\circ}C$   |         | 54<br>285<br>15 |      | ns<br>nC<br>A |

Note:

When using SiC Body Diode the maximum recommended  $V_{GS} = -5V$ 

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#### Package SOT-227B (minibloc)

|                             |                              |                                     |                      |            | Ratir | ngs  |      |
|-----------------------------|------------------------------|-------------------------------------|----------------------|------------|-------|------|------|
| Symbol                      | Definitions                  | Conditions                          |                      | min.       | typ.  | max. | Unit |
| I <sub>RMS</sub>            | RMS current                  | per terminal                        |                      |            |       |      | Α    |
| T <sub>stg</sub>            | storage temperature          |                                     |                      | -40        |       | 150  | °C   |
| T <sub>op</sub>             | operation temperature        |                                     |                      | -40        |       | 150  | °C   |
| T <sub>vj</sub>             | virtual junction temperature |                                     |                      | -40        |       | 175  | °C   |
| Weight                      |                              |                                     |                      |            | 30    |      | g    |
| M <sub>D</sub>              | mounting torque              |                                     |                      | 1.1        |       | 1.5  | Nm   |
| Μ <sub>τ</sub>              | terminal torque              |                                     |                      | 1.1        |       | 1.5  | Nm   |
| <b>d</b> <sub>Spp/App</sub> | ereenen distance en surface  | Latriking distance through air      | terminal to backside | 10.5 / 3.2 |       |      | mm   |
| <b>d</b> <sub>Spb/Apb</sub> | creepage distance on surface | i striking distance through air     | terminal to terminal | 8.6 / 6.8  |       |      | mm   |
| VISOL                       | isolation voltage            | I <sub>ISOL</sub> ≤ 1 mA; 50/60 Hz, | t = 1 sec.           | 3000       |       |      | V    |
|                             |                              |                                     | t = 1 minute         | 2500       |       |      | V    |



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### Outlines SOT-227B (minibloc)



S (4)

| Dim. | Millimeter |       | Inches |       |  |
|------|------------|-------|--------|-------|--|
| Dim. | min        | max   | min    | max   |  |
| Α    | 31.50      | 31.88 | 1.240  | 1.255 |  |
| B    | 7.80       | 8.20  | 0.307  | 0.323 |  |
| С    | 4.09       | 4.29  | 0.161  | 0.169 |  |
| D    | 4.09       | 4.29  | 0.161  | 0.169 |  |
| E    | 4.09       | 4.29  | 0.161  | 0.169 |  |
| F    | 14.91      | 15.11 | 0.587  | 0.595 |  |
| G    | 30.12      | 30.30 | 1.186  | 1.193 |  |
| Н    | 37.80      | 38.23 | 1.488  | 1.505 |  |
| J    | 11.68      | 12.22 | 0.460  | 0.481 |  |
| К    | 8.92       | 9.60  | 0.351  | 0.378 |  |
| L    | 0.74       | 0.84  | 0.029  | 0.033 |  |
| Μ    | 12.50      | 13.10 | 0.492  | 0.516 |  |
| Ν    | 25.15      | 25.42 | 0.990  | 1.001 |  |
| 0    | 1.95       | 2.13  | 0.077  | 0.084 |  |
| Р    | 4.95       | 6.20  | 0.195  | 0.244 |  |
| Q    | 26.54      | 26.90 | 1.045  | 1.059 |  |
| R    | 3.94       | 4.42  | 0.155  | 0.167 |  |
| S    | 4.55       | 4.85  | 0.179  | 0.191 |  |
| Т    | 24.59      | 25.25 | 0.968  | 0.994 |  |
| U    | -0.05      | 0.10  | -0.002 | 0.004 |  |
| V    | 3.20       | 5.50  | 0.126  | 0.217 |  |
| W    | 19.81      | 21.08 | 0.780  | 0.830 |  |
| Ζ    | 2.50       | 2.70  | 0.098  | 0.106 |  |

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